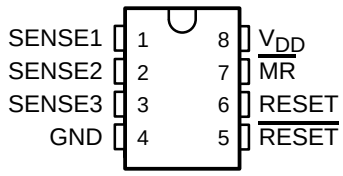
- **Qualification in Accordance With AEC-Q100†**
- **Qualified for Automotive Applications**
- **Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Triple Supervisory Circuits for DSP and Processor-Based Systems**
- **Power-On Reset Generator with Fixed Delay Time of 200 ms, No External Capacitor Needed**

† Contact factory for details. Q100 qualification data available on request.

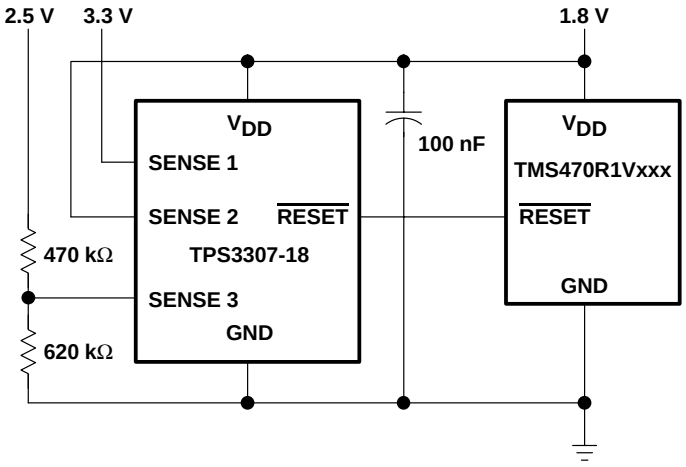
- **Temperature-Compensated Voltage Reference**
- **Maximum Supply Current of 40 μA**
- **Supply Voltage Range . . . 2 V to 6 V**
- **Defined $\overline{\text{RESET}}$ Output from $V_{DD} \geq 1.1$ V**
- **SO-8 Package**
- **Temperature Range . . . –40°C to 125°C**

D PACKAGE
(TOP VIEW)



typical applications

Figure 1 lists some of the typical applications for the TPS3307 family, and a schematic diagram for a processor-based system application. This application uses TI part numbers TPS3307–18 and TMS470R1Vxxx.



- **Automotive applications using DSPs, Microcontrollers or Microprocessors**
- **Industrial Equipment**
- **Programmable Controls**
- **Automotive Systems**

Figure 1. Applications Using the TPS3307-18

description

The TPS3307-18 is a micropower supply voltage supervisor designed for circuit initialization primarily in automotive DSP and processor-based systems, which require more than one supply voltage.

The TPS3307-18 is designed for monitoring three independent supply voltages: 3.3 V/1.8 V/adj,. The adjustable SENSE input allows the monitoring of any supply voltage >1.25 V.

The various supply voltage supervisors are designed to monitor the nominal supply voltage as shown in the following supply voltage monitoring table.

description (continued)

SUPPLY VOLTAGE MONITORING

DEVICE	NOMINAL SUPERVISED VOLTAGE			THRESHOLD VOLTAGE (TYP)		
	SENSE1	SENSE2	SENSE3	SENSE1	SENSE2	SENSE3
TPS3307-18	3.3 V	1.8 V	User defined	2.93 V	1.68 V	1.25 V†

† The actual sense voltage has to be adjusted by an external resistor divider according to the application requirements.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors the SENSEn inputs and keeps $\overline{\text{RESET}}$ active as long as SENSEn remain below the threshold voltage V_{IT+}.

An internal timer delays the return of the $\overline{\text{RESET}}$ output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d\,typ}$ = 200 ms, starts after all SENSEn inputs have risen above the threshold voltage V_{IT+}. When the voltage at any SENSE input drops below the threshold voltage V_{IT-}, the $\overline{\text{RESET}}$ output becomes active (low) again.

The TPS3307-18 incorporates a manual reset input, $\overline{\text{MR}}$. A low level at $\overline{\text{MR}}$ causes $\overline{\text{RESET}}$ to become active. In addition to the active-low $\overline{\text{RESET}}$ output, the TPS3307-18 includes an active-high RESET output.

The device is available in a standard 8-pin SO package, and is characterized for operation over a temperature range of –40°C to 125°C.

ORDERING INFORMATION

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	Small Outline (D)	Tape and Reel	TPS3307-18QDRQ1	30718Q

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION/TRUTH TABLES

$\overline{\text{MR}}$	SENSE1>V_{IT1}	SENSE2>V_{IT2}	SENSE3>V_{IT3}	$\overline{\text{RESET}}$	RESET
L	X	X	X	L	H
H	0	0	0	L	H
H	0	0	1	L	H
H	0	1	0	L	H
H	0	1	1	L	H
H	1	0	0	L	H
H	1	0	1	L	H
H	1	1	0	L	H
H	1	1	1	H	L

X = Don't care

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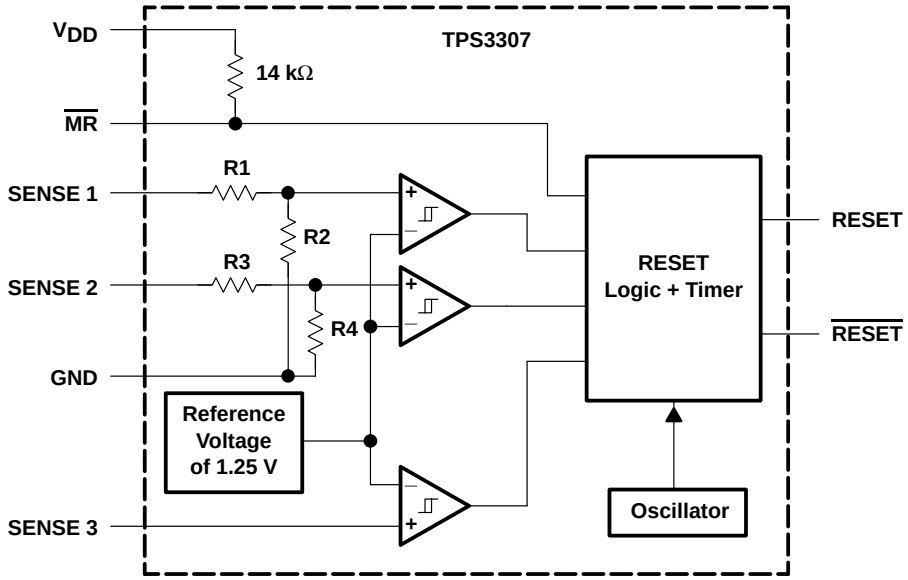
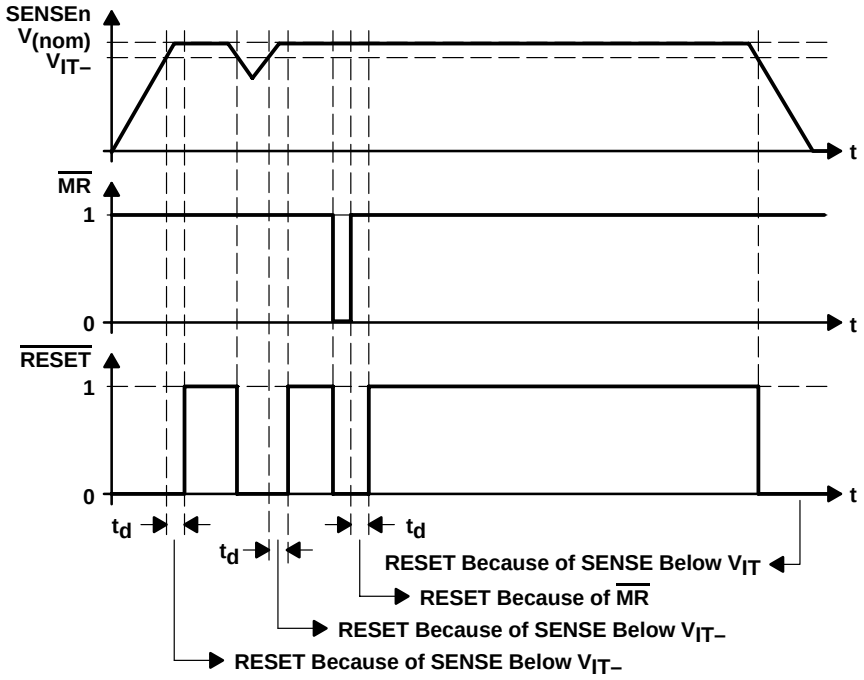
functional block diagram



timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} (see Note1) . . . . . 7 V
All other pins (see Note 1) . . . . . –0.3 V to 7 V
Maximum low output current, I_{OL} . . . . . 5 mA
Maximum high output current, I_{OH} . . . . . –5 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$) . . . . . ±20 mA
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . –40°C to 125°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Soldering temperature . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device must not be operated at 7 V for more than t = 1000 h continuously.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V_{DD}	2	6	V
Input voltage at $\overline{MR}$ and SENSE3, V_I	0	V_{DD}+0.3	V
Input voltage at SENSE1 and SENSE2, V_I	0	(V_{DD}+0.3)V_{IT}/1.25V	V
High-level input voltage at $\overline{MR}$, V_{IH}	0.7xV_{DD}		V
Low-level input voltage at $\overline{MR}$, V_{IL}		0.3×V_{DD}	V
Input transition rise and fall rate at $\overline{MR}$, $\Delta t/\Delta V$		50	ns/V
Operating free-air temperature range, T_A	–40	125	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage		V_{DD} = 2 V to 6 V, I_{OH} = –20 μA	V_{DD}– 0.2V			V
			V_{DD} = 3.3 V, I_{OH} = –2 mA	V_{DD}– 0.4V			
			V_{DD} = 6 V, I_{OH} = –3 mA	V_{DD}– 0.4V			
V_{OL}	Low-level output voltage		V_{DD} = 2 V to 6 V, I_{OL} = 20 μA			0.2	V
			V_{DD} = 3.3 V, I_{OL} = 2 mA			0.4	
			V_{DD} = 6 V, I_{OL} = 3 mA			0.4	
	Power-up reset voltage (see Note 2)		$V_{DD} \geq$ 1.1 V, I_{OL} = 20 μA			0.4	V
V_{IT-}	Negative-going input threshold voltage (see Note 3)	VSENSE3	V_{DD} = 2 V to 6 V, T_A = –40°C to 125°C	1.2	1.25	1.29	V
		VSENSE2		1.6	1.68	1.73	V
		VSENSE1		2.8	2.93	3.02	
V_{hys}	Hysteresis at VSENSEn input		V_{IT-} = 1.25 V	2	10	30	mV
			V_{IT-} = 1.68 V	2	15	40	
			V_{IT-} = 2.93 V	3	30	60	
I_H	High-level input current	$\overline{MR}$	$\overline{MR}$ = 0.7 × V_{DD}, V_{DD} = 6 V		–130	–180	μA
		SENSE1	VSENSE1 = V_{DD} = 6 V		5	8	
		SENSE2	VSENSE2 = V_{DD} = 6 V		6	9	
		SENSE3	VSENSE3 = V_{DD}	–1		1	
I_L	Low-level input current	$\overline{MR}$	$\overline{MR}$ = 0 V, V_{DD} = 6 V		–430	–600	μA
		SENSEn	VSENSE1,2,3 = 0 V	–1		1	
I_{DD}	Supply current					40	μA
C_i	Input capacitance		V_I = 0 V to V_{DD}		10		pF

NOTES: 2. The lowest supply voltage at which $\overline{RESET}$ becomes active. t_r, $V_{DD} \geq$ 15 μs/V
3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic 0.1 μF) should be placed close to the supply terminals.

timing requirements at V_{DD} = 2 V to 6 V, R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Pulse width	SENSEn	$V_{SENSEnL} = V_{IT-} - 0.2$ V, $V_{SENSEnH} = V_{IT+} + 0.2$ V	6	10		µs
		$\overline{MR}$	$V_{IH} = 0.7 \times V_{DD}$, $V_{IL} = 0.3 \times V_{DD}$	100	150		ns

switching characteristics at V_{DD} = 2 V to 6 V, R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_d	Delay time		$V_{I(SENSEn)} \geq V_{IT+} + 0.2$ V, $\overline{MR} \geq 0.7 \times V_{DD}$, See timing diagram	140	200	280	ms
t_{PHL}	Propagation (delay) time, high-to-low level output	$\overline{MR}$ to $\overline{RESET}$ $\overline{MR}$ to RESET	$V_{I(SENSEn)} \geq V_{IT+} + 0.2$ V, $V_{IH} = 0.7 \times V_{DD}$, $V_{IL} = 0.3 \times V_{DD}$		200	600	ns
t_{PLH}	Propagation (delay) time, low-to-high level output	$\overline{MR}$ to $\overline{RESET}$ $\overline{MR}$ to RESET					
t_{PHL}	Propagation (delay) time, high-to-low level output	SENSEn to $\overline{RESET}$	$V_{IH} = V_{IT+} + 0.2$ V, $V_{IL} = V_{IT-} - 0.2$ V, $\overline{MR} \geq 0.7 \times V_{DD}$		1	5	µs
t_{PLH}	Propagation (delay) time, low-to-high level output	SENSEn to RESET					

TYPICAL CHARACTERISTICS

NORMALIZED SENSE THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE AT V_{DD}

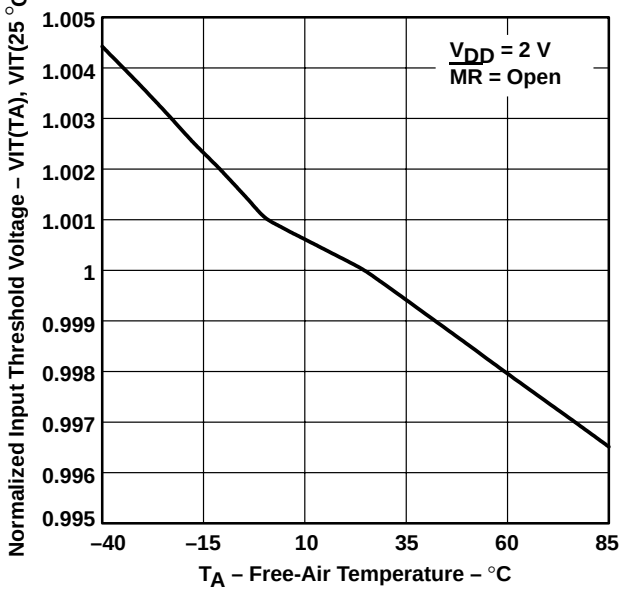


Figure 2

SUPPLY CURRENT vs SUPPLY VOLTAGE

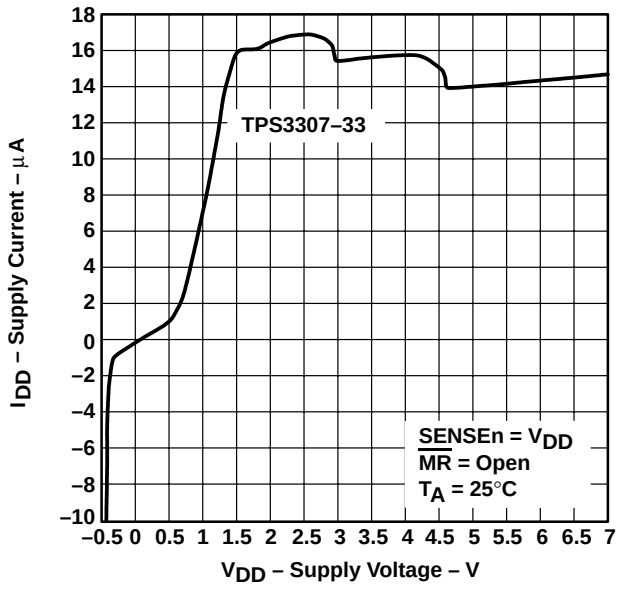


Figure 3

INPUT CURRENT vs INPUT VOLTAGE AT $\overline{MR}$

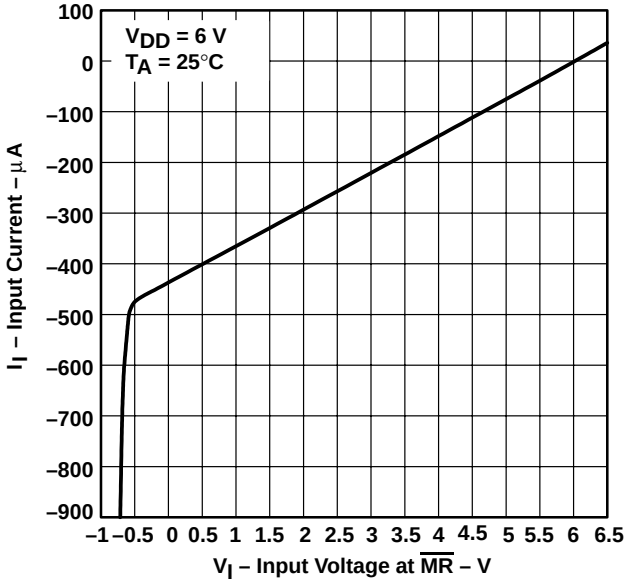


Figure 4

MINIMUM PULSE DURATION AT SENSE vs THRESHOLD OVERDRIVE

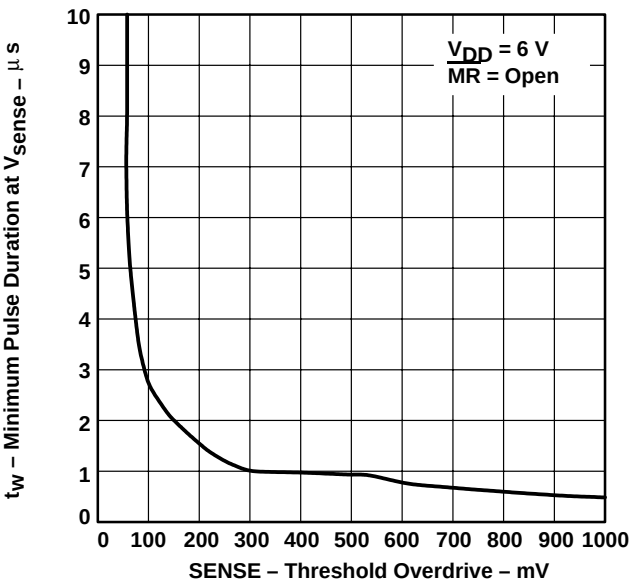


Figure 5

TYPICAL CHARACTERISTICS

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

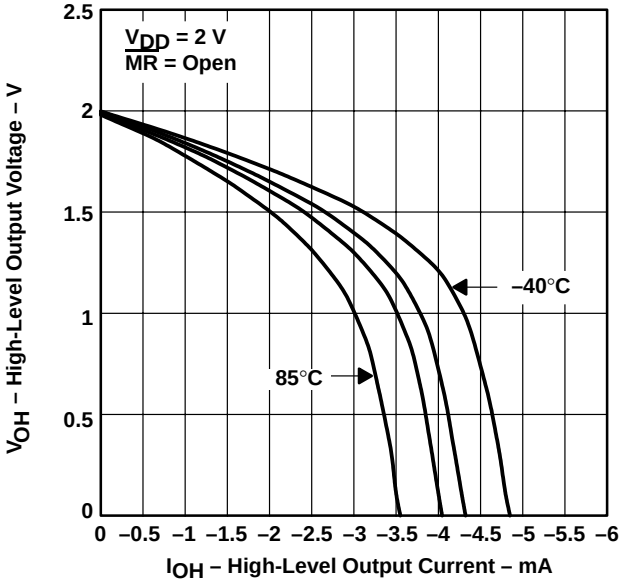


Figure 6

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

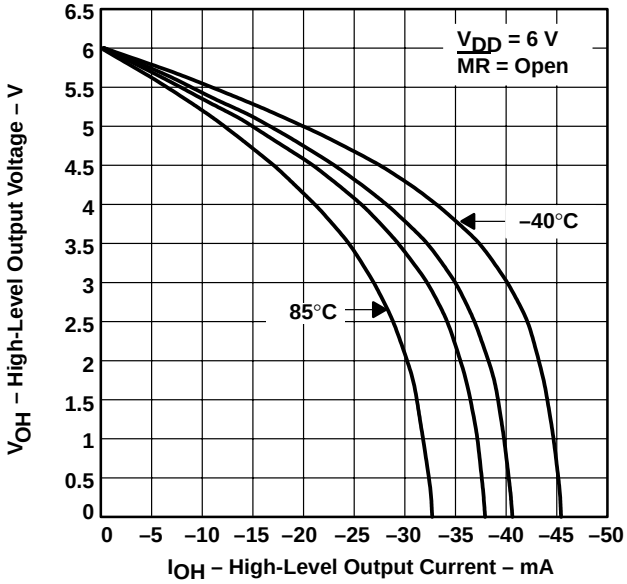


Figure 7

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

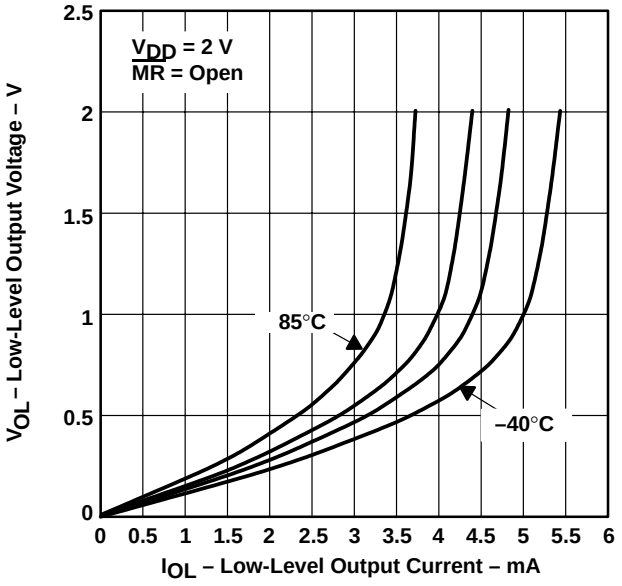


Figure 8

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

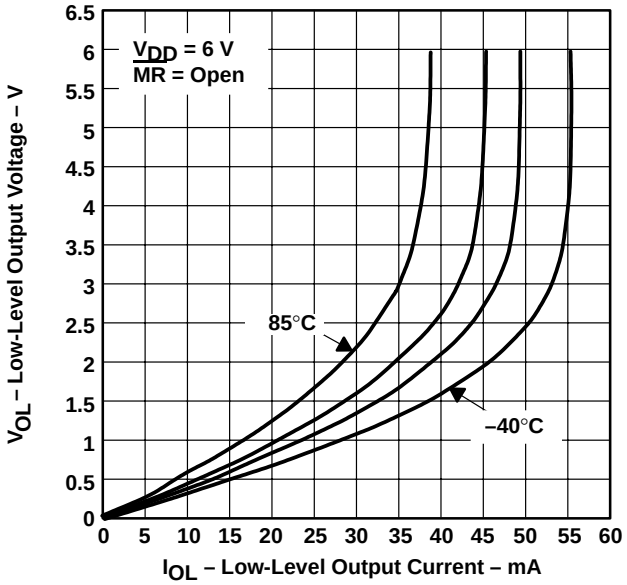
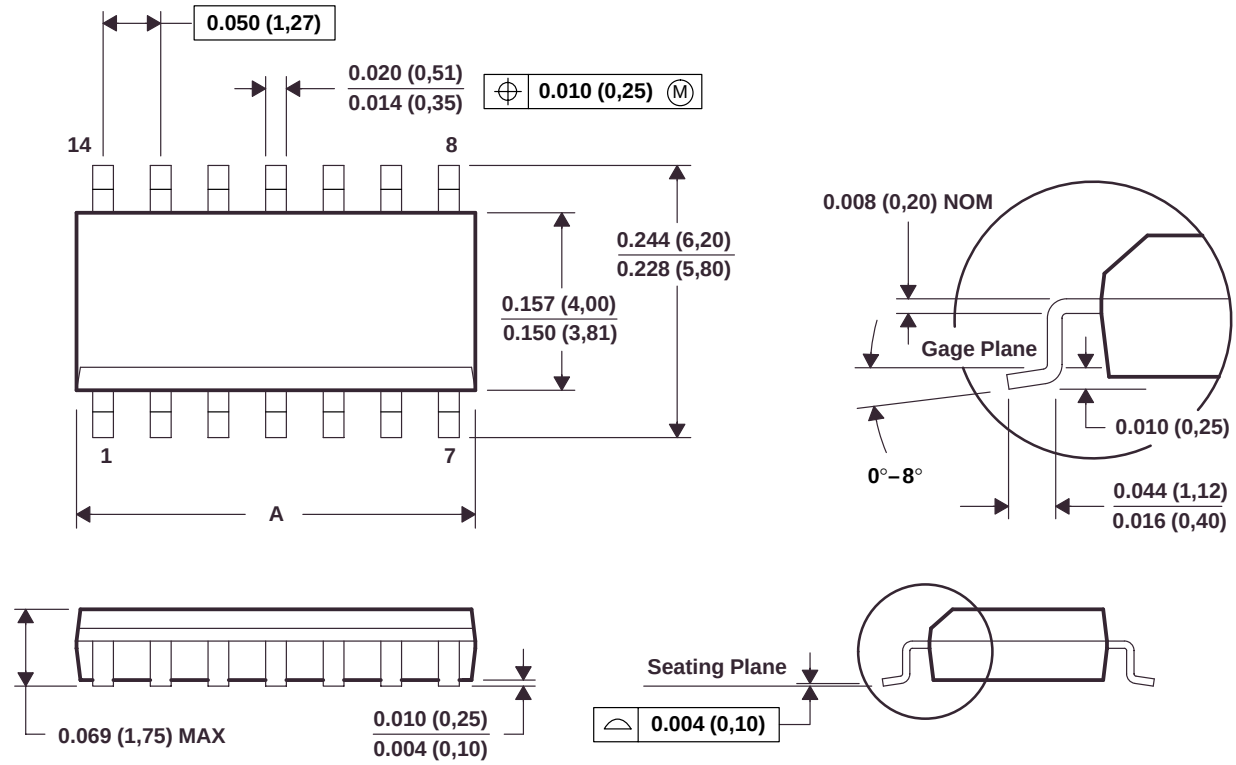


Figure 9

MECHANICAL DATA

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN



DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

4040047/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

PACKAGING INFORMATION

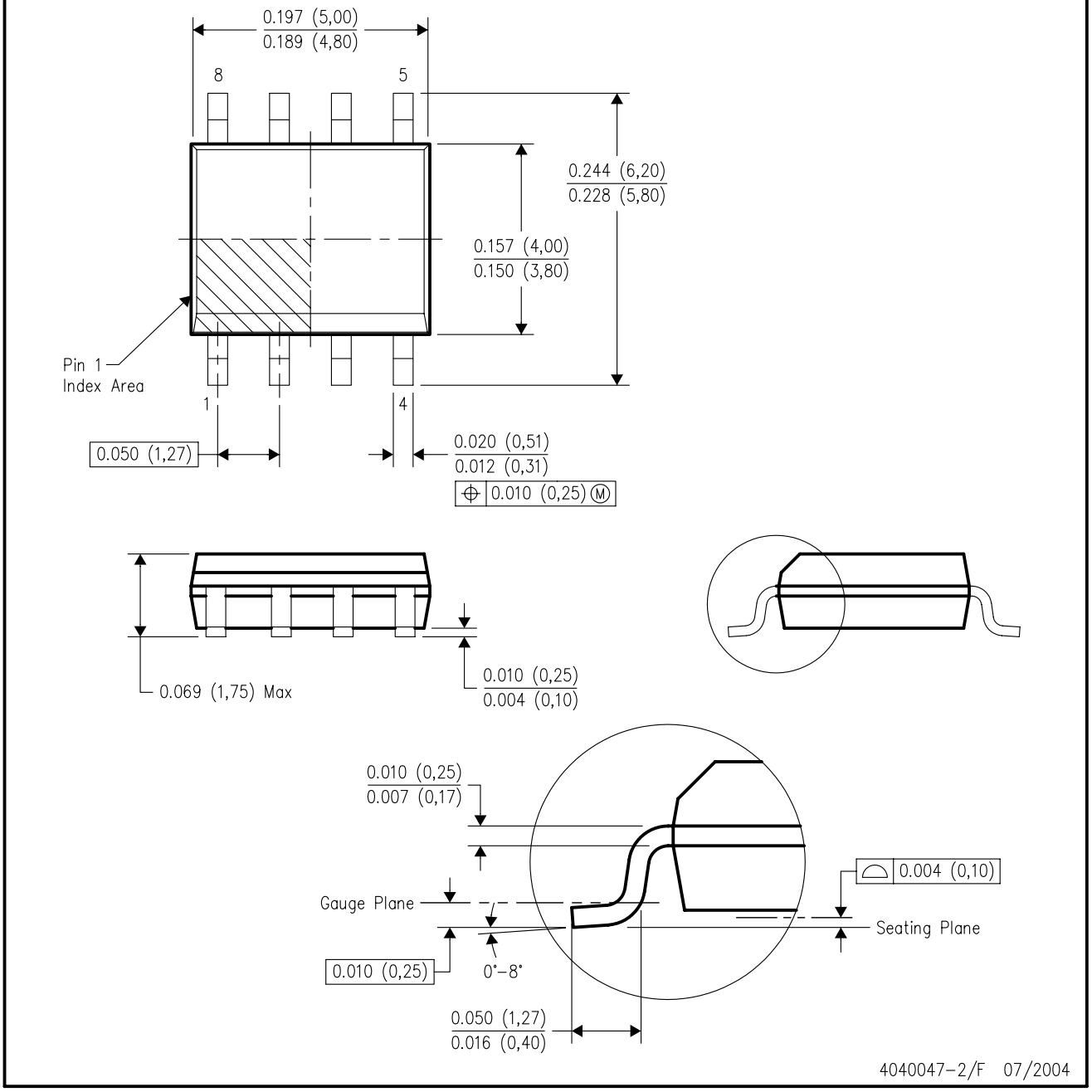
Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TPS3307-18QDRQ1	ACTIVE	SOIC	D	8	2500	None	CU NIPDAU	Level-1-220C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AA.

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265